

## REMARKS

Claims 1-10 are pending and under consideration. In the Office Action of April 20, 2005, claims 1-10 were rejected under 35 U.S.C. §103(a) as obvious over *Kiely, et al.* (USP 5,953,355) in view of *Uemura, et al.* (USPubl. 2002/0043331A). This rejection is traversed.

Independent claims 1 and 6 each claim irradiating a laser chip and base after bonding a wire-bonded wiring. This subject matter is discussed, for example, in Applicant's specification with reference to Figures 9 and 10. As discussed in the illustrative example, wires 36A and 36B are bonded (see Figures 9 and 10) and "[a]fter that, as shown in FIG. 10, the base 31 having the laser chip 20 mounted thereon is irradiated with an energy beam EB." (Specification, page 10, lines 13-19).

This is clearly unlike *Kiely* in view of *Uemura*, which fails to disclose or suggest irradiating a laser chip and body after bonding a wire-bonded wire. As acknowledged by the Examiner, *Kiely* discloses a wire-bonded wire, but fails to disclose irradiating a laser chip and body. The Examiner therefore combines *Kiely* with *Uemura* in attempt to disclose or suggest the claimed invention, however, Applicants respectfully submit the combination still fails to disclose or suggest irradiating a laser chip and body after bonding a wire-bonded wire.

Although *Uemura* teaches irradiating a laser chip, *Uemura* specifically teaches away from Applicant's claims 1 and 6 by teaching that it irradiates prior to bonding in order to improve reliability of the bonding:

Irradiation with ultraviolet rays can be carried out at desired timing. There is a clear possibility that organic contaminations are produced when photolithography is carried out. It is therefore preferable that irradiation with ultraviolet rays is performed whenever the photolithography is carried out. Further, it is preferable that, also after the wafer is cut into chips, the chips are irradiated with ultraviolet rays. Thus, the reliability of ball bonding to the p-type seat electrode or the n-type seat electrode is improved.

(*Uemura*, [0021]) (emphasis added).

The Examiner echoes *Uemura's* teaching by arguing that *Kiely* would benefit from *Uemura's* irradiation prior to bonding *Kiely's* wires. (Office Action of 4/20/2005, page 3). Thus, *Kiely* in view of *Uemura* fails to disclose or suggest irradiating a laser chip and body after bonding a wire-bonded wire.

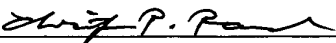
Accordingly, *Kiely* in view of *Uemura* clearly fails to disclose or suggest claims 1 and 6.

Claims 2-5 and 7-10 depend directly or indirectly from claim 1 or 6 and are therefore allowable for at least the same reasons that claims 1 and 6 are allowable.

Applicants respectfully submit the rejection has been overcome and request that it be withdrawn.

It is submitted that claims 1-10 are patentable and that the application is in condition for allowance. Notice to that effect is requested.

Respectfully submitted,

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